



D Top View

N-Channel 20 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a			
20	0.0043 at V _{GS} = 10 V	34			
	0.006 at V _{GS} = 4.5 V	28			

TO-252 Drain Connected to Tab

Ordering Information: SUD50N02-04P-E3 (Lead (Pb)-free)

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized for High Efficiency
- Material categorization: definitions compliance see please www.vishay.com/doc?99912

APPLICATIONS

- Synchronous Buck Converter
 - Low-Side
 - Desktop, Servers, Desknote
- Synchronous Rectification
 - POL

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)							
Parameter		Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	20	V			
Gate-Source Voltage	V _{GS}	± 20	V				
	T _A = 25 °C	- I _D	34 ^a				
Continuous Drain Current ^a	T _C = 25 °C		50 ^b				
Pulsed Drain Current	I _{DM}	100	Α				
Continuous Source Current (Diode Conduction) ^a	I _S	8.3 ^a					
Avalanche Current ^c	L = 0.1 mH	I _{AS}	50				
Avalanche Energy ^c	L = 0.1 IIII1	E _{AS}	125	mJ			
Maximum Power Discination	T _A = 25 °C	P _D	8.3 ^a	w			
Maximum Power Dissipation	T _C = 25 °C	1 'D	136				
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C			

N-Channel MOSFET

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Marian and Lucation to Ambient	t ≤ 10 s	R _{thJA}	15	18	°C/W		
Maximum Junction-to-Ambient ^a	Steady State		40	50			
Maximum Junction-to-Case		R _{thJC}	0.85	1.1			

Notes:

- a. Surface mounted on FR4 board, $t \le 10$ s.
- b. Limited by package.
- c. Single pulse.

SUD50N02-04P

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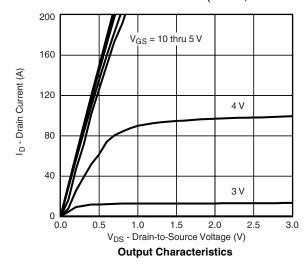
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	20			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.8		3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valta da Duain Comuna	l	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	иА	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
		V _{GS} = 10 V, I _D = 20 A		0.0035	0.0043	Ω	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.0061		
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0048	0.006		
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$	15			S	
Dynamic ^a							
Input Capacitance	C _{iss}			5000		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 10 \text{ V}, f = 1 \text{ MHz}$		1650			
Reverse Transfer Capacitance	C _{rss}			770			
Gate Resistance	R_g	f = 1 MHz		1.6		Ω	
Total Gate Charge ^c	Q_g			40	60		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 50 \text{ A}$		14		nC	
Gate-Drain Charge ^c	Q_{gd}			13			
Turn-On Delay Time ^c	t _{d(on)}			20	30		
Rise Time ^c	t _r	V_{DD} = 10 V, R_L = 0.2 Ω		20	30	ne	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		50	75	ns	
Fall Time ^c	t _f			15	25		
Source-Drain Diode Ratings and Cha	racteristics	T _C = 25 °C					
Pulsed Current	I _{SM}				100	Α	
Diode Forward Voltage ^b	V_{SD}	I _F = 50 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	$I_{F} = 50 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		45	70	ns	

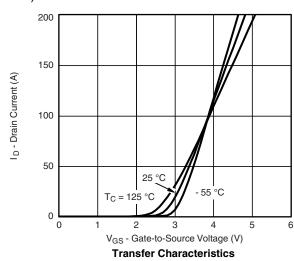
Notes:

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



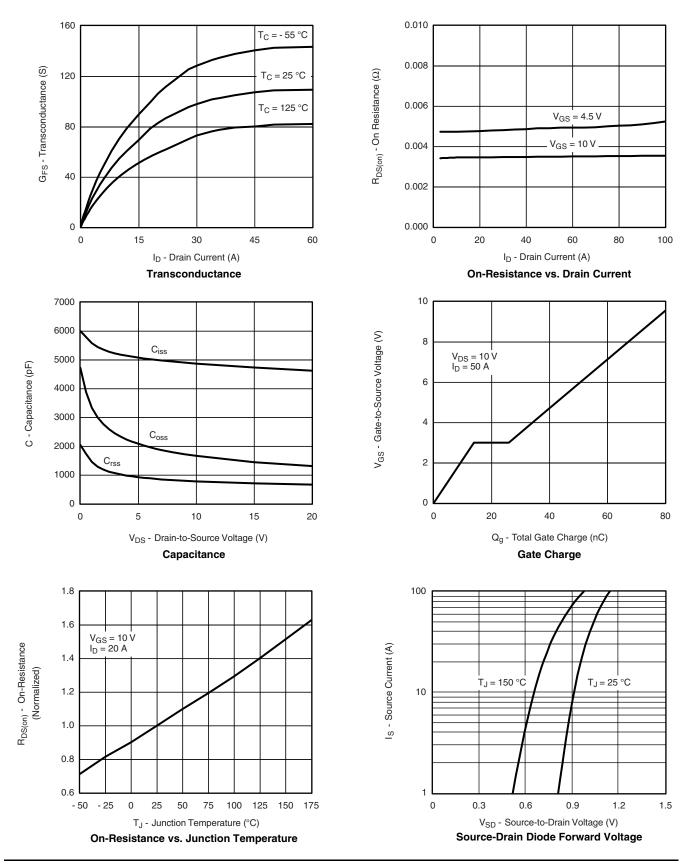


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For technical questions, contact: pmostechsupport@vishay.com



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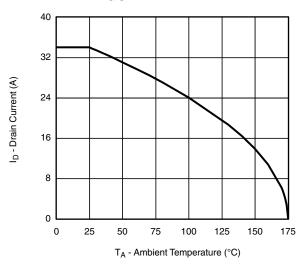


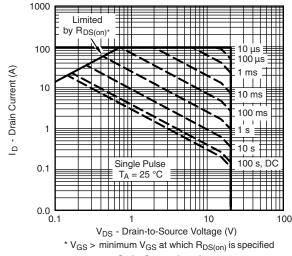
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Normalized Effective Transient Thermal Impedance

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THERMAL RATINGS





Max. Avalanche and Drain Current vs.
Ambient Temperature





Normalized Thermal Transient Impedance, Junction-to-Ambient

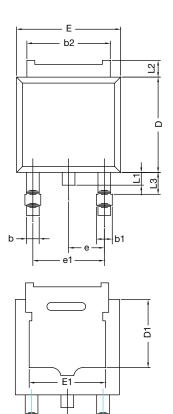
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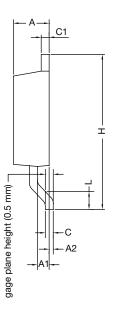
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TO-252AA CASE OUTLINE





	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
A2	0.030	0.127	0.001	0.005	
b	0.71	0.88	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.44	0.206	0.214	
С	0.46	0.58	0.018	0.023	
C1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
D1	4.10	4.45	0.161	0.175	
Е	6.48	6.73	0.255	0.265	
E1	4.49	5.50	0.177	0.217	
е	2.28 BSC		0.090	BSC	
e1	4.57 BSC		0.180	BSC	
Η	9.65	10.41	0.380	0.410	
L	1.40	1.78	0.055	0.070	
L1	0.64	1.02	0.025	0.040	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.040	0.060	
ECN: T11-0110-Rev. L, 18-Apr-11 DWG: 5347					

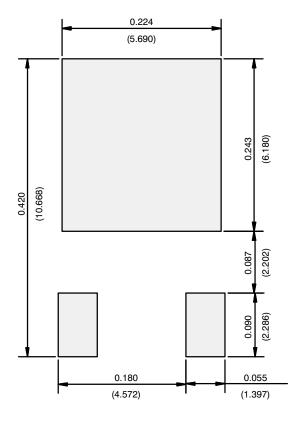
Note

• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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